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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof		
Name of conveying party(ies):	Name and address of receiving party(ies)	
Syozo Kasai (12/10/2003), Takayasu Furukawa (12/03/2003), Ryoji Inaba (12/03/2003), Daiki Numai (12/03/2003), and Tomoyuki Tobita (12/03/2003)	Name: Hitachi High-Technologies Corporation Internal Address:	
Additional name(s) of conveying party(ies) 3. Nature of Conveyance: X Assignment Security Agreement Other Execution Date: December 10, 2003	Street Address: 24-14, Nishishimbashi 1-chome Minato-ku Tokyo JAPAN City: State: Additional name(s) & Zip: Address(es) attached:	
Application number(s) or patent number(s):		
If this document is being filed together with a new application, the exe A. Patent Application No.(s): 10/732,221 Additional numbers attached	B. Patent No.(s):	
Name and address of party to whom correspondence concerning document should be mailed:	Total number of applications and patents involved: 1	
Name: Mark J. Thronson DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP	7. Total fee (37 CFR 3.41) \$ 40.00	
Internal Address: Atty. Dkt.: H6808.0029/P029	Enclosed	
Street Address: 2101 L Street NW	Authorized to be charged to deposit account Authorized to be charged to credit card (Form 2038 enclosed)	
City: State: Zip: DC 20037-1526	8. Deposit account number: 04-1073 (Attach duplicate copy of this page if paying by deposit account)	
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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Mark J. Thronson (33,082) Name of Person Signing April 13, 2004 Date		
Total number of pages including cover sheet, attachments, and documents:		

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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan,

located at 24-14, Nishishimbashi 1-chome, Minato-ku, Tokyo, Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

CAPILLARY ARRAY APPARATUS, METHOD OF MANUFACTURING THE SAME, AND ELECTROPHORESIS ANALYSIS METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

RECORDED: 04/13/2004

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Syozo Kasai</u>	12/10/2003
2) Jakayasu Furukawa	12/3/2003
3) Ryoji Inaba	12/3/2003
4) Daiki humai	12/3/2003
5) Tomoyuki Tobita	12/3/ 2003
6)	
7)	
8)	
9)	
10)	

PATENT REEL: 015213 FRAME: 0472